Data Sheet- EddyCus® TF map 6060 Series

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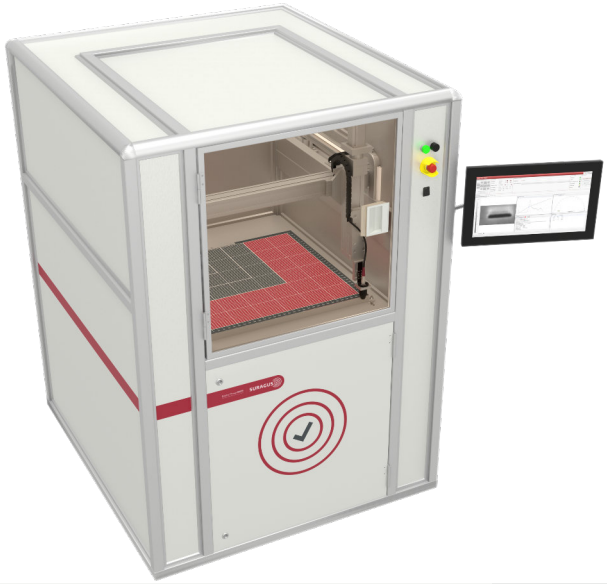

Highlights

- Electrical integrity imaging
- High resolution imaging (25 to 1,000,000 points)
- Defect imaging
- Mapping of encapsulated layers

Parameters

- Sheet resistance (Ohm/sq)
- Metal layer thickness (nm, µm)
- Metal substrate thickness (µm)
- Anisotropy
- Defects detection
- Integrity assessment

Applications

- Architectural glass (LowE)
- Touch screens and flat monitors
- OLED and LED applications
- Smart-glass applications
- Photovoltaics
- Semiconductors
- De-icing and heating applications
- Batteries and fuel cells
- Packaging materials

Materials

- Metal films and meshes
- Conductive oxides
- Nanowire films
- Graphite
- Printed films
- Conductive polymers (PEDOT:PSS)
- Other conductive films and materials

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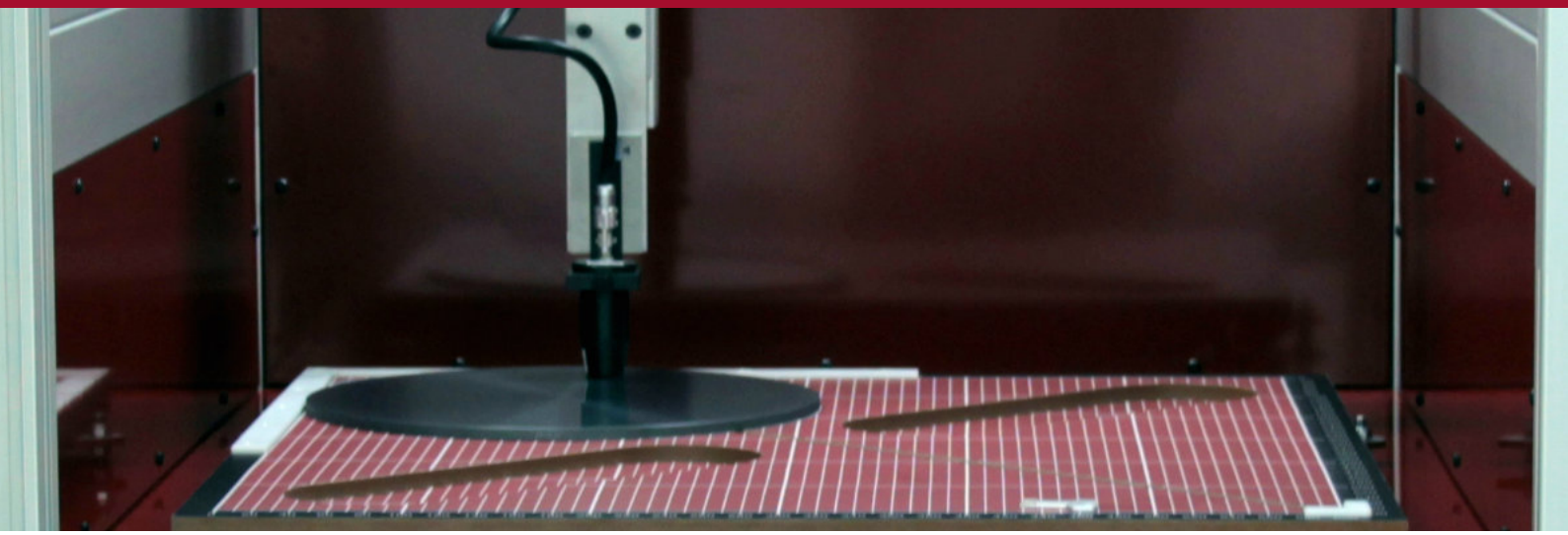
Made and Engineered in Germany

Innovation Award by Free State of Saxony 2013
1st Place

EddyCus® TF map 6060 Series



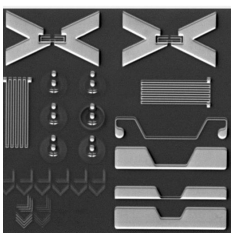
Measurement technology	Non-contact eddy current sensor
Parts geometry	Flat, slightly curved
Max. Scanning area	600 x 600 x 150 mm
Edge effect correction / exclusion	2 - 5 mm edge exclusion for standard sizes
Max. Sample thickness / sensor gap	150 mm
Sheet resistance range and accuracy	0.005 - 50 Ohm/sq 0.01- 65 MS/m (70- 0.016 µOhm*m)
Thickness measurement of metal films (e.g. aluminum, copper)	2 nm - 2 mm (in accordance with sheet resistance)
Min. Pitch	0.1 mm
Mode	Contact and non-contact
Speed	400 mm per second (time 1 to 30 minutes)
Device dimension (w/l/ h) / weight	1,200 x 1,700 x 1,350 mm
Available features	Metal thickness imaging

Device Control and Software

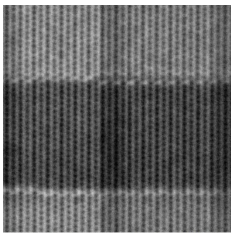
- Control via touch panel
- Easy setup of scanning parameters
- Pre-defined measurement recipes
- Storage and import of data
- Export of data sets (eg. to EddyEva, MS Excel, Origin)

Advanced Analysis Software EddyEva

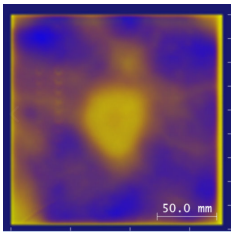
- 2D and 3D data evaluation
- Dynamic GUI design
- Advanced impedance analysis
- Allowing various data views
- Standard and smart evaluation algorithms
- Defect / effect size determination
- Determination of evaluation recipes
- Saving and applying existing recipes
- Loading and reanalyzing data sets
- Anomaly detection



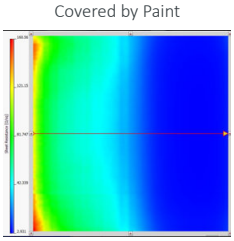
Printed Test Structures



Copper Mesh on CFRP Covered by Paint



SiC Composition / Resistivity Varation



Deposition Gradiant of Capacitor Foil